GP Component

NOTES:
1. MATERIAL:
   HOUSING: HIGH TEMPERATURE THERMOPLASTIC
   UL94V_0,COLOR:LCP(BLACK).
   CONTACT: COPPER ALLOYS.T=0.2
   COVER: COPPER ALLOYS OR STEEL. T=0.2.
2. PLATING:
   UNDERPLATE: NICKEL 100U"MIN.
   CONTACT AREA: GOLD(1U") OVER NICKEL 100U" MIN.
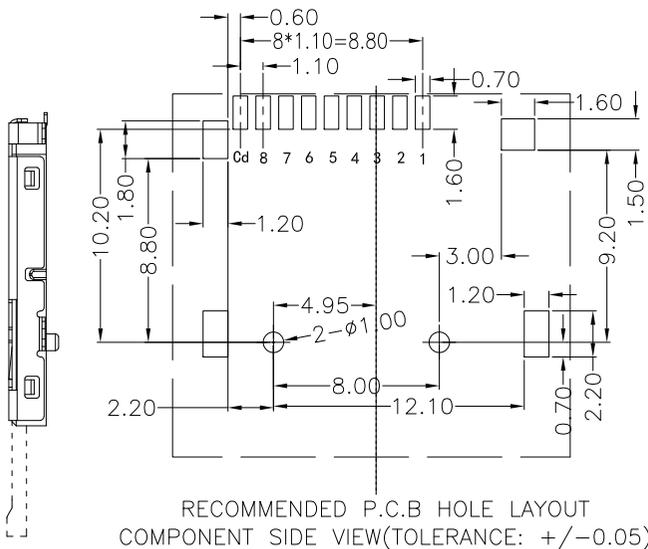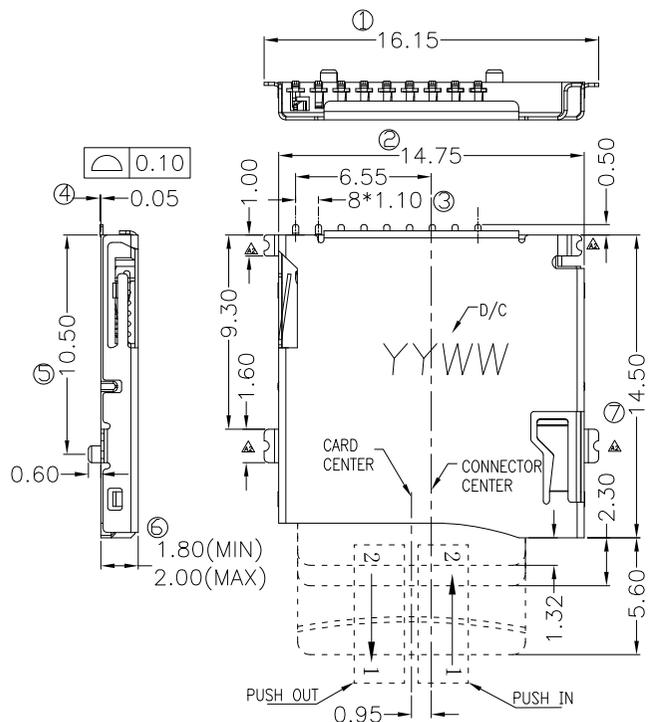   SOLDER AREA: TIN 100U" MIN OVER NICKEL 50U" MIN.
3. MULTIMEDIA CARD COMPATIBLE
4. PERFORMANCE:
   DURABILITY : 10000 MATING CYCLES
   TOTAL MATING FORCE : 9.8N MAXIMUM
   POP-UP FORCE : 2.65 N

MATRIX PART NO:
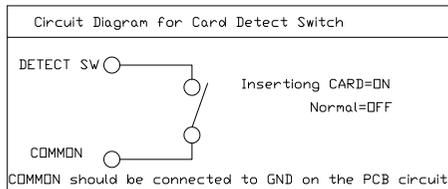
MMS - 01 - 01 - 08 - 20 - 06

Matrix
Micro SD
01:Push
02:Non-Push
Gold Plating
01:1u"
30:30u"
Height
Pin number
06:6pin
08:8pin
Series Number

RECOMMENDED P.C.B HOLE LAYOUT
COMPONENT SIDE VIEW(TOLERANCE: +/-0.05)

YYWW

D/C

CARD CENTER
CONNECTOR CENTER

PUSH OUT
PUSH IN

T-Flash
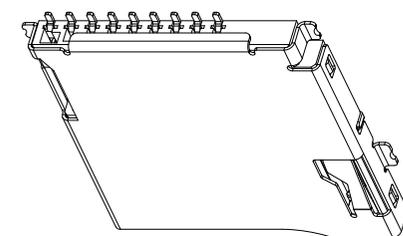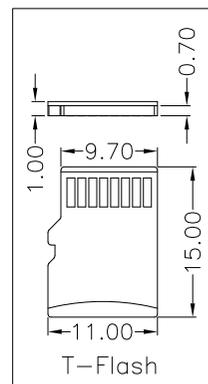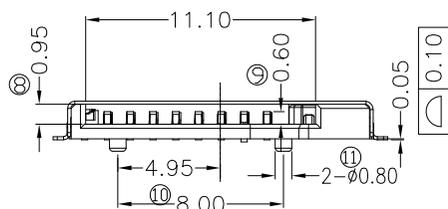
PIN NO.	NAME	YTPE	DESCRIPTION
1	DAT2	I/O/PP	DATE LINE(BIT2)
2	CD/DAT3	I/O/PP	CARD DETECT DATE LIN(BIT3)
3	CMD	PP	COMMAND RESPONSE
4	VDD	S	SUPPLY VOLTAGE
5	CLX	I	CLOCK
6	VSS	S	SUPPLY VOLTAGE GROUND
7	DAT0	I/O/PP	DATE LINE(BIT0)
8	DAT1	I/O/PP	DATE LINE(DIT1)

Circuit Diagram for Card Detect Switch

DETECT SW

Insertiong CARD=ON
Normal=OFF

COMMON

COMMON should be connected to GND on the PCB circuit

Matrix Electronics Co.,Ltd

TOLERANCE:
X:x
X:x ±0.20
X.XX ±0.15
X.XXX ±0.10
ANGLE: ±3°

UNIT: mm [inch]

SCALE:1:1 SIZE:A4

	DESIGN BY :	DATE :	PART NAME:
	Summer Wang	2018/11/30	Micro SD push Outside welding
	CHECKED BY:	DATE :	PART NO. MMS-01-01-08-20-06
	Vicky Hsieh	2018/11/30	
	APPROVED BY1:	DATE :	MOLD NO. NA
	Richard Hsieh	2018/11/30	
	APPROVED BY2:	DATE :	DRAW NO.
	Richard Hsieh	2018/11/30	SHEET NO. 1 OF 1